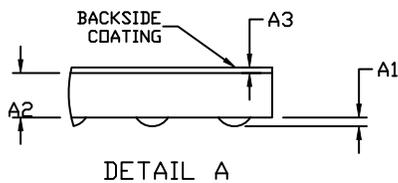
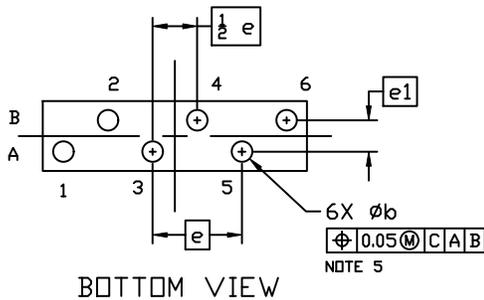
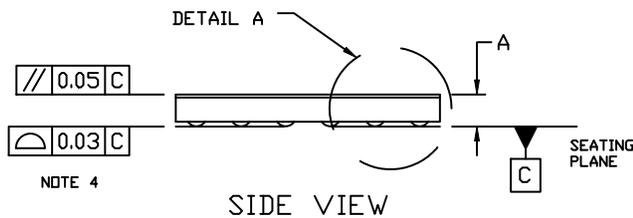
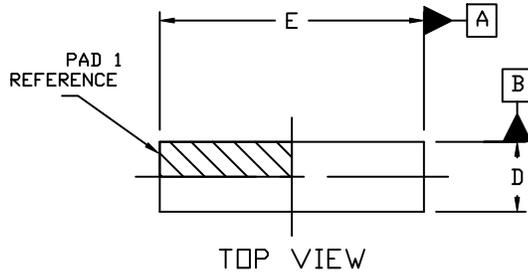




**WLCSP6, 0.58x2.19x0.265**  
CASE 567XY  
ISSUE C

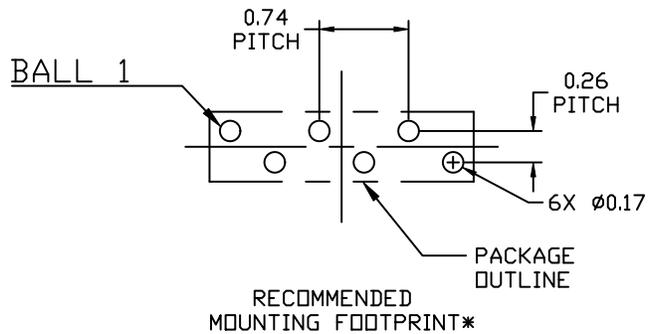
DATE 23 JUN 2021



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPHERICAL CROWNS OF THE CONTACT BALLS.
4. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE CONTACT BALLS.
5. DIMENSION b IS MEASURED AT THE MAXIMUM CONTACT BALL DIAMETER PARALLEL TO DATUM C.

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.24	0.265	0.29
A1	0.04 REF		
A2	0.20 REF		
A3	0.025 REF		
b	0.12	0.17	0.22
D	0.53	0.58	0.63
E	2.14	2.19	2.24
e	0.74 BSC		
e1	0.26 BSC		



**GENERIC MARKING DIAGRAM\***



XXXX = Specific Device Code  
A = Assembly Location  
L = Wafer Lot  
Y = Year  
W = Work Week

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

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<b>DESCRIPTION:</b>	<b>WLCSP6, 0.58x2.19x0.265</b>	<b>PAGE 1 OF 1</b>

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